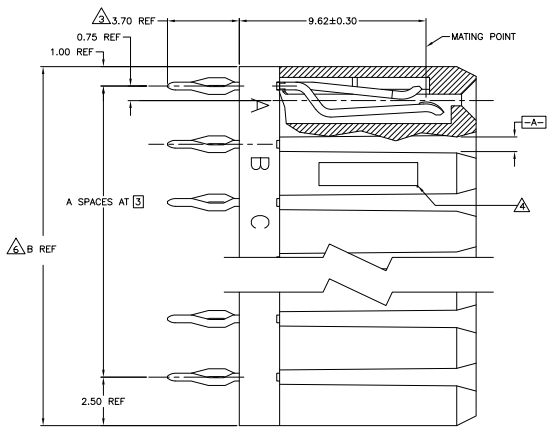
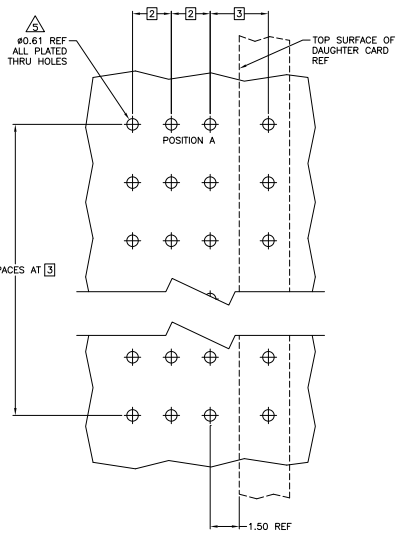
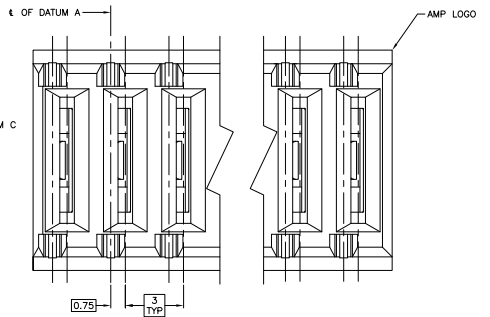
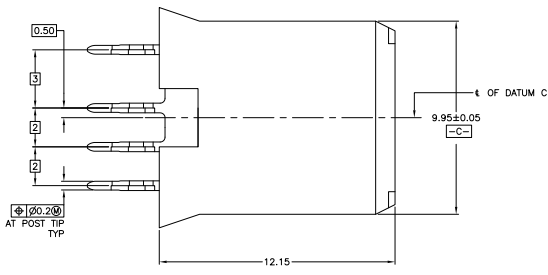
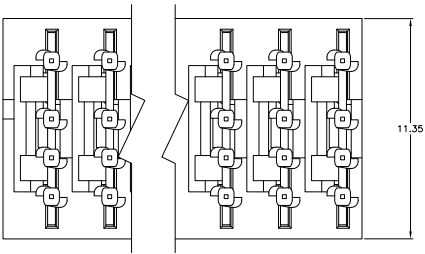


THIS DRAWING IS UNPUBLISHED  
 ALL RIGHTS RESERVED

REV	DESCRIPTION	DATE	BY	APP
AD 00	REVISED PER EDD-11-004835	11MAR11	RK	HMR

- 1 MATERIAL: HOUSING : POLYESTER, COLOR, GRAY, UL 94V-0.  
CONTACT: PHOSPHOR BRONZE.
- 2 FINISH: CONTACT MATING AREA: 1.27µm MINIMUM GOLD OR 0.08µm MIN GOLD OVER  
0.76µm MIN PALLADIUM-NICKEL  
ACTION PIN AREA, 0.5µm MINIMUM TIN PLATE,  
ALL OVER 1.27µm MINIMUM NICKEL UNDERPLATE.
- 3 TOLERANCE TO BE ±0.28 AFTER CONNECTOR IS APPLIED TO PC BOARD.
- 4 DATE CODE THIS APPROXIMATE AREA, OPPOSITE SIDE.
- 5 REFERENCE APPLICATION SPEC 114-1103 FOR  
RECOMMENDED PLATED THRU HOLE DIAMETER AND  
PLATING THICKNESS.
- 6 TOLERANCE TO BE +0.5/-0.1 BEFORE CONNECTOR IS APPLIED TO PC BOARD.
- 7 CURRENT RATING 10A/CONTACT PER PRODUCT SPEC 108-1651.



RECOMMENDED PCB HOLE LAYOUT

12	36.5	11	5223995-9
11	33.5	10	5223995-8
10	30.5	9	5223995-7
9	27.5	8	5223995-6
8	24.5	7	5223995-5
7	21.5	6	5223995-4
6	18.5	5	5223995-3
5	15.5	4	5223995-2
4	12.5	3	5223995-1

THIS DRAWING IS A CONTROLLED DOCUMENT. **TE** CONNECTIVITY

RECEPTACLE ASSEMBLY, UNIVERSAL POWER MODULE

DATE: 10/07/09 DRAWING NO: 100779 REV: 10-1

CUSTOMER DRAWING